Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12518E DC Switch Chassis(JG785A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2 from the chassis.
2. Unscrew the screws on front panel 3, and then remove front panel 3 from the chassis.
3. Unscrew the screws on front panel 4, and then remove front panel 4 from the chassis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on front panel 6, and then remove front panel 6 from the chassis.
6. Unscrew the screws on plastic panel 7, and then remove plastic panel 7 from the chassis.
7. Remove plastic logo panel 8 from the chassis.
8. Remove plastic panel 9 from the chassis.
9. Remove plastic panel 10 from the chassis.
10. Unscrew the screws on cable management bracket 11, and then remove cable management bracket 11 from the chassis.
11. Remove film 12 from the chassis.
12. Unscrew the screws on power locking plate 13, and then remove power locking plate 13 from the chassis.
13. Unscrew the screws on power locking plate 14, and then remove power locking plate 14 from the chassis.
14. Unscrew the screws on part 15, and then remove part 15 from the chassis.
15. Unscrew the screws on power chassis 16, and then remove power chassis 16 from the chassis.
16. Unscrew the screws on front panel 17, and then remove front panel 17 from the chassis.
17. Unscrew the screws on back cover 18, and then remove back cover 18 from the chassis.
18. Unscrew the screws on fan tray 19, and then remove fan tray 19 from the chassis.
19. Unscrew the screws on front panel 20, and then remove front panel 20 from the chassis.
20. Unscrew the screws on part 21, and then remove part 21 from the chassis.
21. Unscrew the screws on panel 22, and then remove panel 22 from the chassis.
22. Unscrew the screws on part 23, and then remove part 23 from the chassis.
23. Unscrew the screws on part 24, and then remove part 24 from the chassis.
24. Unscrew the screws on busbar cover 25, 26 and 27, and then remove them from the chassis.
25. Unscrew the screws on busbar 28, and then remove busbar 28 from the chassis.
26. Unscrew the screws on PCB 29, and then remove PCB 29 from the chassis.
27. Unscrew the screws on part 30, and then remove part 30 from the chassis.
28. Unscrew the screws on part 31, and then remove part 31 from the chassis.
29. Unscrew the screws on backboard 32, and then remove backboard 32 from the chassis.
30. Remover all of the EMI fingers from the chassis.
31. Remove all of the labels and films.
32. Unscrew the screws on PCB 3-1, and then remove PCB 3-1 from the front panel 3.
33. Unscrew the screws on PCB 3-2, and then remove PCB 3-2 from the front panel 3.
34. Remove conductive foamfrom 3-4 from front panel 3.
35. Remove film 3-5 from front panel 3.
36. Remove shielding finger 3-6 from front panel 3.
37. Unscrew the screws on pcb 4-1, pcb 4-2, pcb 4-3 and heat sink 4-4, then remove the pcb 4-1, pcb 4-2, pcb 4-3 and heat sink 4-4 from front panel 4-5.
38. Unscrew the screws on front panel 4-6, then remove front panel 4-6 from front panel 4-5.
39. Unscrew the screws on guiding set 4-7, and then remove guiding set 4-7 from pcb 4-1.
40. Unscrew the screws on front panel 4-6, then remove front panel 4-6 from front panel 4-5.
41. Remove shielding finger 4-8 from front panel 4-6.
42. Remove film 4-9 from front panel 4-6.
43. Remove film 5-1 from the front panel 5.
44. Remove EMI finger 5-2 from the front panel 5.
45. Unscrew the screws on air filter 7-1, and then remove air filter 7-1 from the plastic panel 7.
46. Unscrew the screws on hinges 7-2, and then remove hinges 7-2 from the plastic panel 7.
47. Unscrew the screws on part 11-1, and then remove part 11-1 from the cable management bracket 11.
48. Unscrew the screws on part 11-2, and then remove part 11-2 from the cable management bracket 11.
49. Unscrew the screws on part 11-3, and then remove part 11-3 from the cable management bracket 11.

50. Unscrew the screws on cover 16-1, and then remove cover 16-1 from power frame 16-2.
51. Unscrew the screws on PCB 16-3, and then remove PCB 16-3 from power frame 16-2.
52. Remove all of the inner cables from power frame 16-2.
53. Unscrew the screws on busbar 16-4, and then remove busbar 16-4 from power frame 16-2.
54. Unscrew the screws and double-screw bolt on PCB 16-5, and then remove PCB 16-5 from power frame 16-2.
55. Unscrew the screws on cover 16-6, and then remove cover 16-6 from power frame 16-2.
56. Unscrew the screws on cable receptacle 16-5,then remove cable receptacle 16-5 from power frame 16-2.
57. Remove switch 16-7 from power frame 16-2.
58. Remove film 16-8 from power frame 16-2.
59. Unscrew the screws on switch shiedling 16-9,then remove switch shiedling 16-9 from power frame 16-2.
60. Unscrew the screws on pcb 17-1, then remove pcb 17-1 from front panel 17-2.
61. Remove film 17-3 from front pane 17-2.
62. Remove shielding finger 17-4 from front panel 17-2.
63. Unscrew the screws on protection cover 19-1 and protection cover 19-2, and then remove protection cover 19-1 and protection cover 19-2 from fan frame 19-5.
64. Unscrew the screws on fan protect net 19-4,fan protect net 19-5,fan 19-6 and fan 19-7, and then remove protect net 19-3,fan protect net 19-4,fan 19-6 and fan 19-7 from fan frame 19-5.
65. Unscrew the screws on pcb 19-8,then remove the pcb 19-8 from fan frame 19-5.
66. Unscrew the screws on handle 19-9, and then remove handle 19-9 from fan frame 19-5.
67. Remove shielding finger 19-10 from fan frame 19-5.
68. Remove film 19-11 from from fan frame 19-5.
69. Remove handle warning label 19-12 and fan caution label 19-13 from from fan frame 19-5.
70. Unscrew the screws on pcb 20-1 and pcb 20-2, then remove pcb 20-1 and pcb 20-2 from front panel 20-3.
71. Remove film 20-4 from front pane 20-3.
72. Remove shielding finger 20-5 from front panel 20-3.
73. Remove film 22-1 from the panel 22.
74. Remove shielding finger 22-2 from the panel 22.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

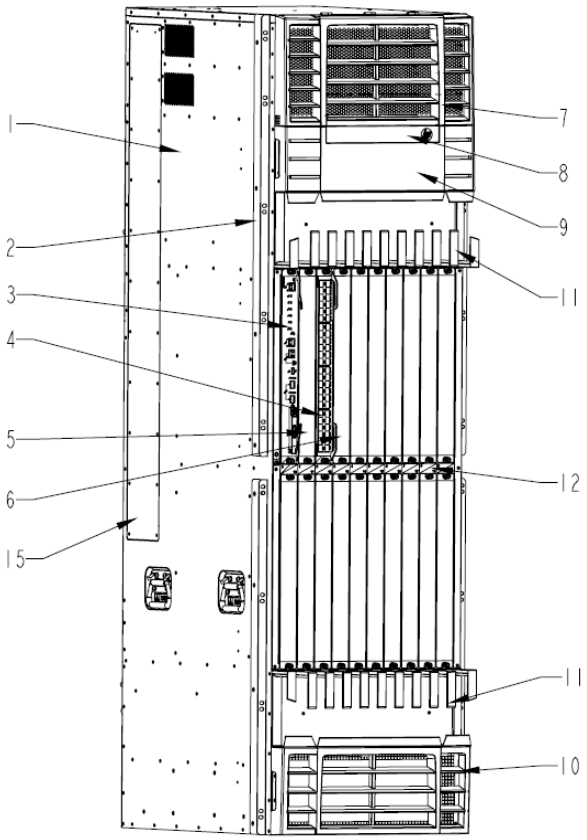

Figure 1 Treatments to the product (front view)

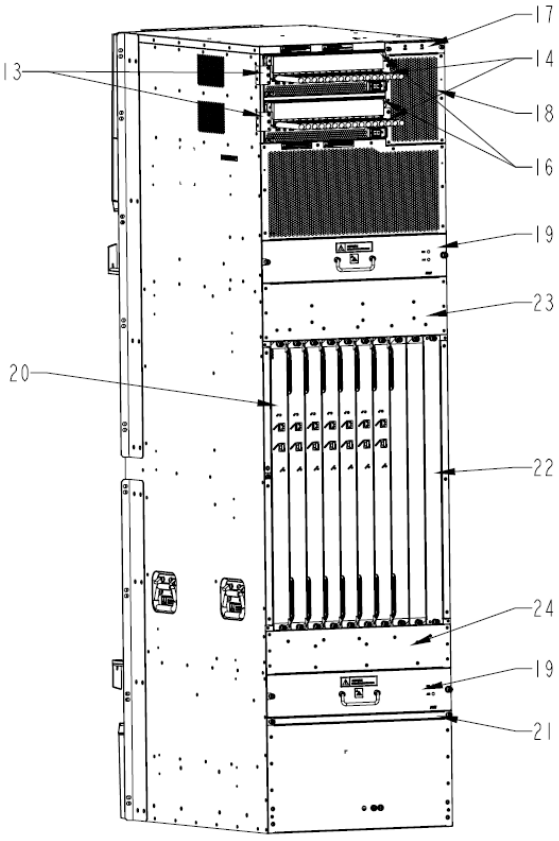

Figure 2 Treatments to the product (rear view)

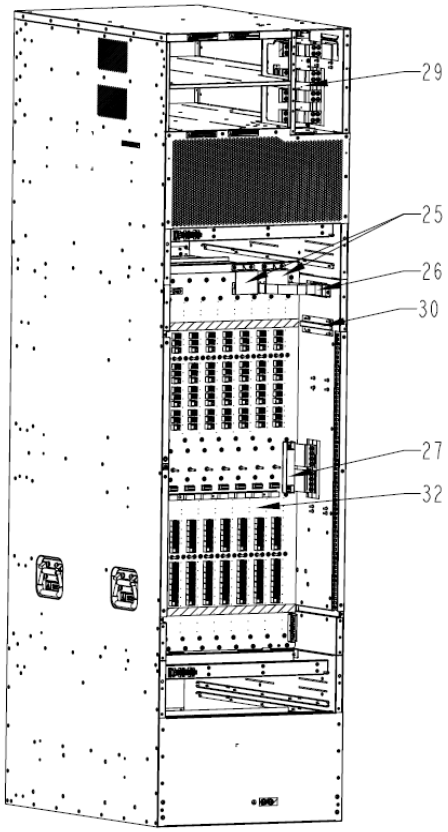

Figure 3 Remove the backboard (rear view)

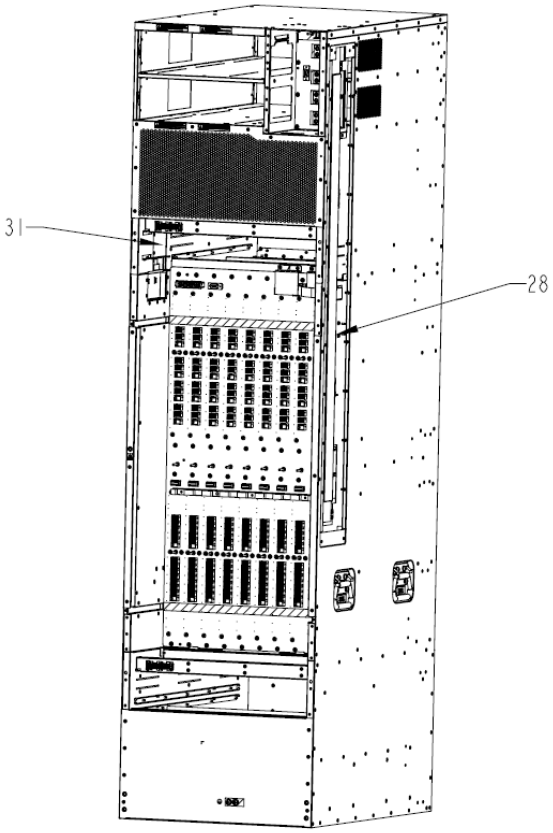

Figure 4 Remove the backboard (rear view)

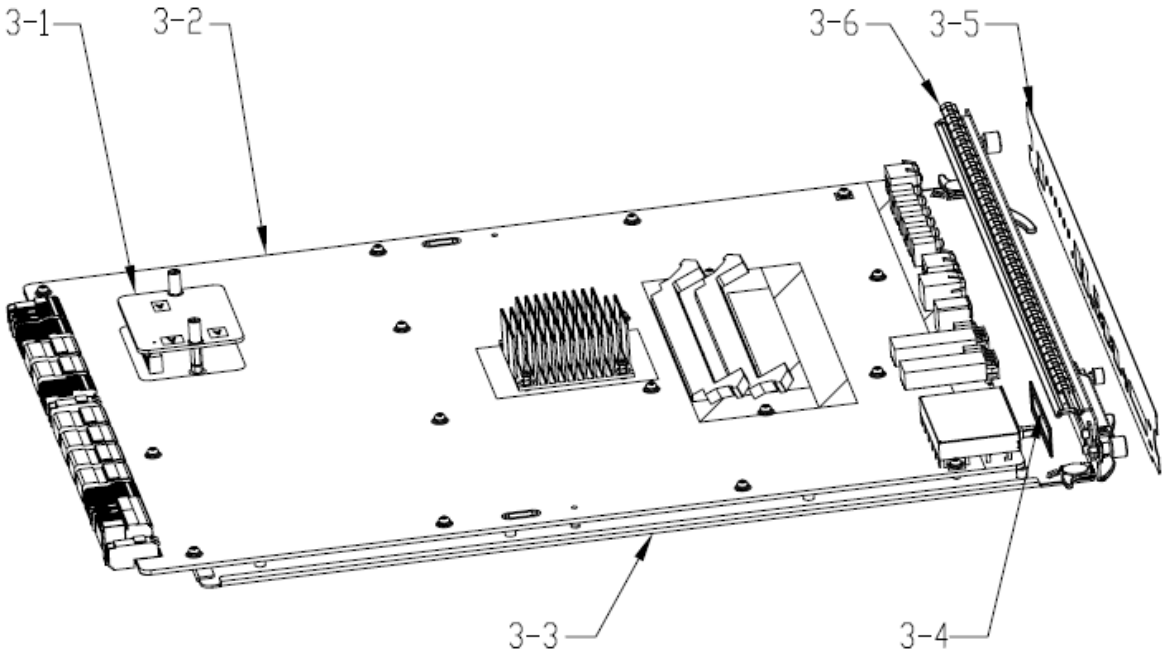

Figure 5 Treatments to front panel 3

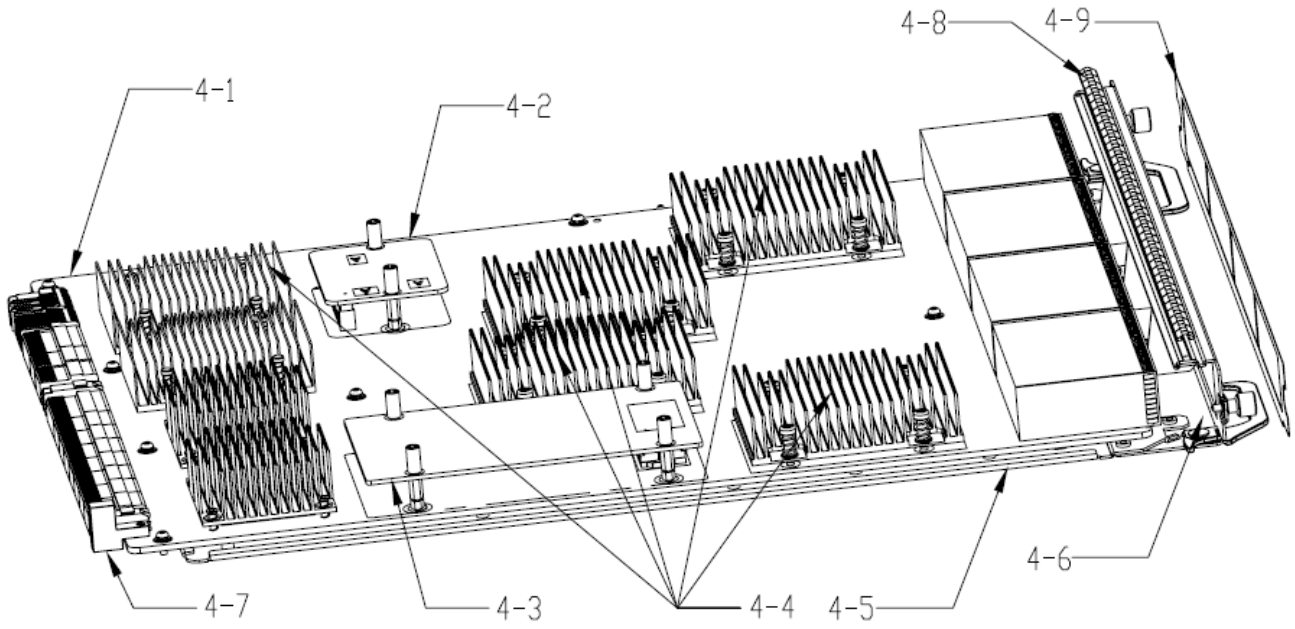

Figure 6 Treatments to front panel 4

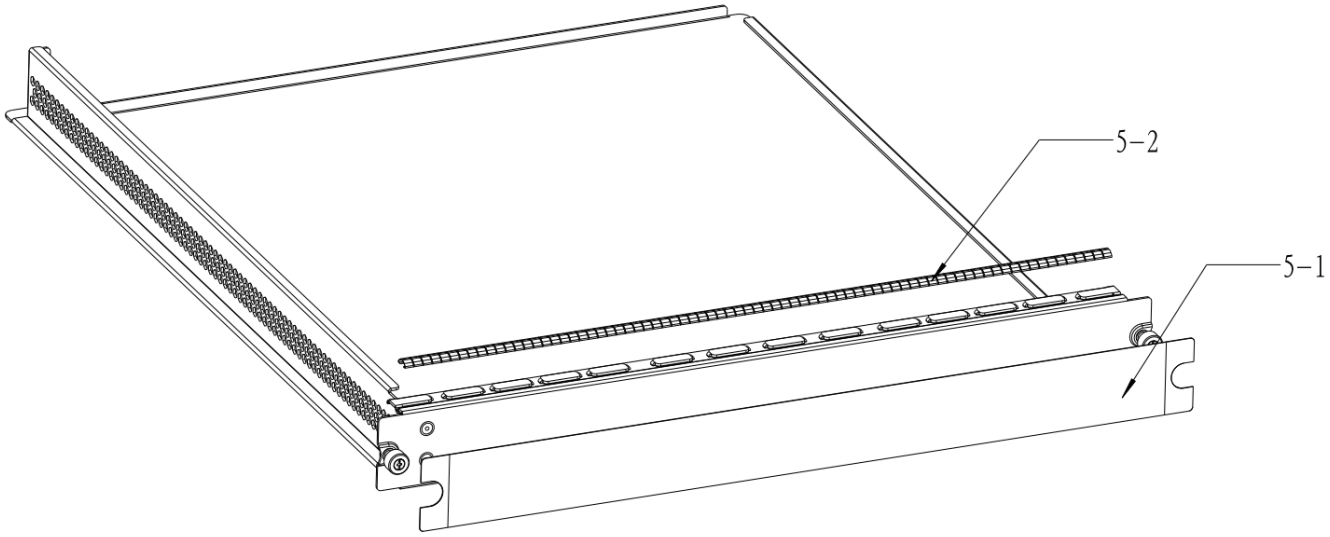

Figure 7 Treatments to front panel 5

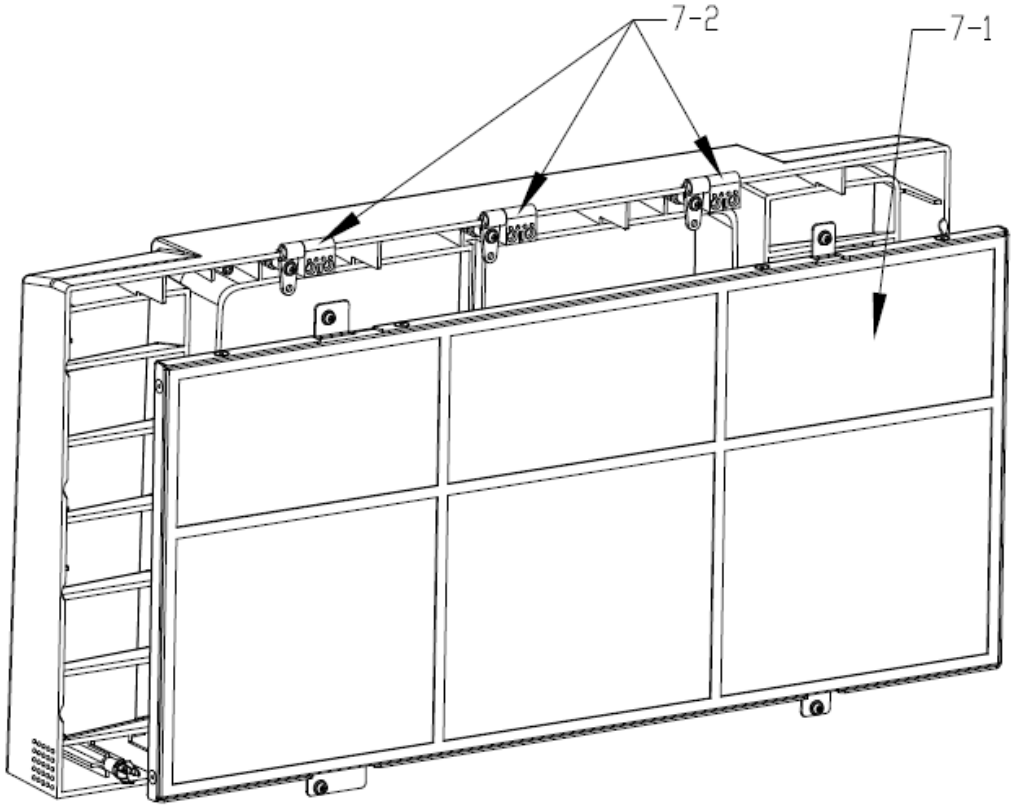

Figure 8 Treatments to plastic panel 7

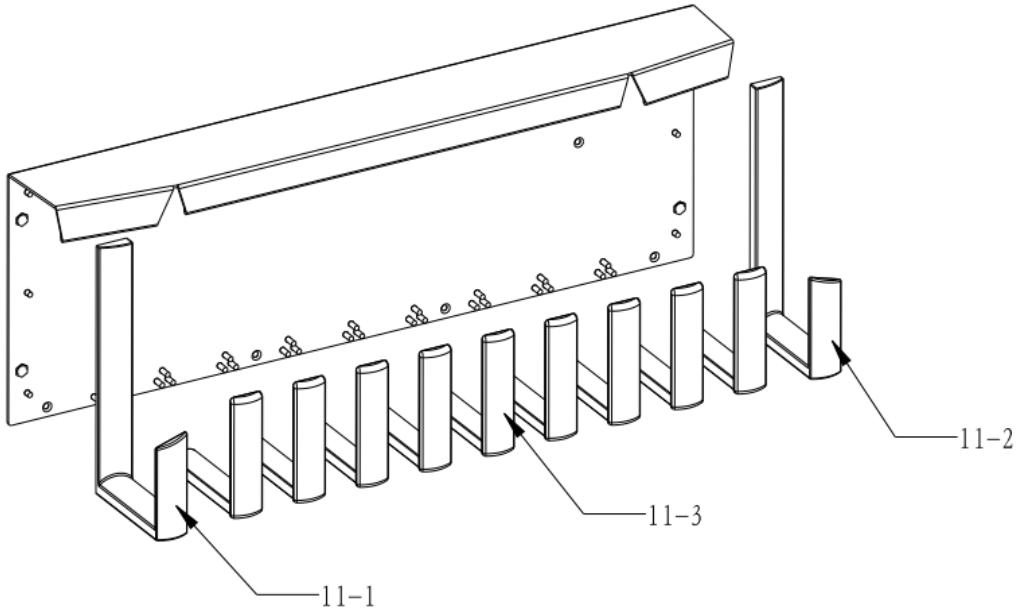

Figure 9 Treatments to cable management bracket 11

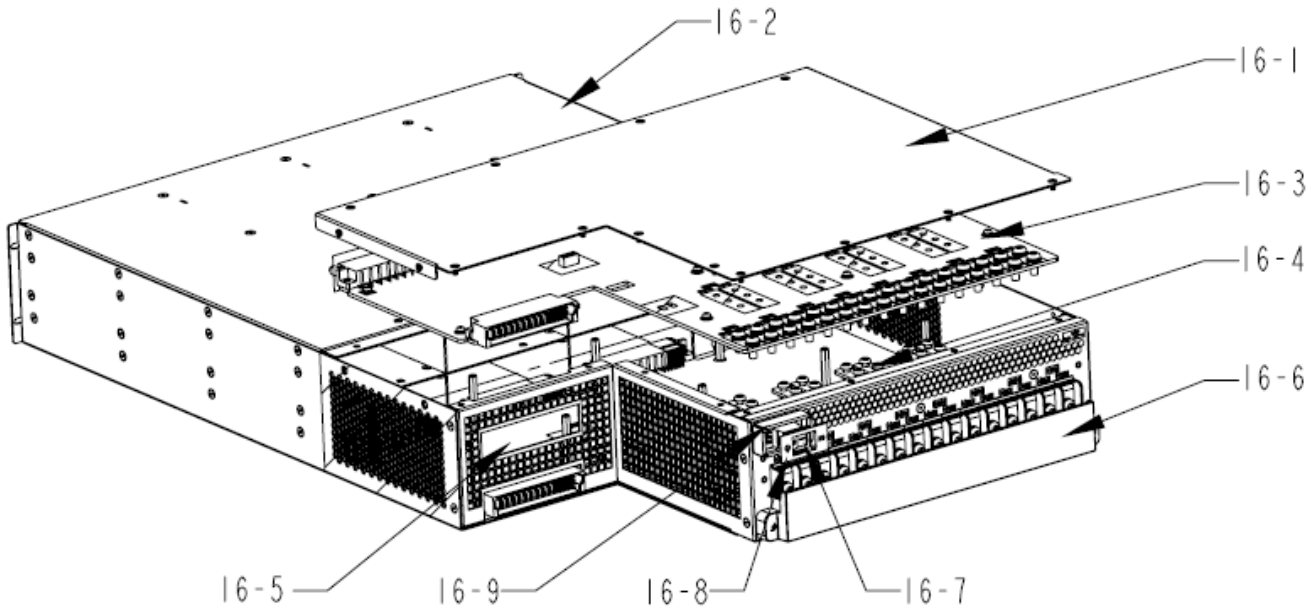

Figure 10 Treatments to power chassis 16

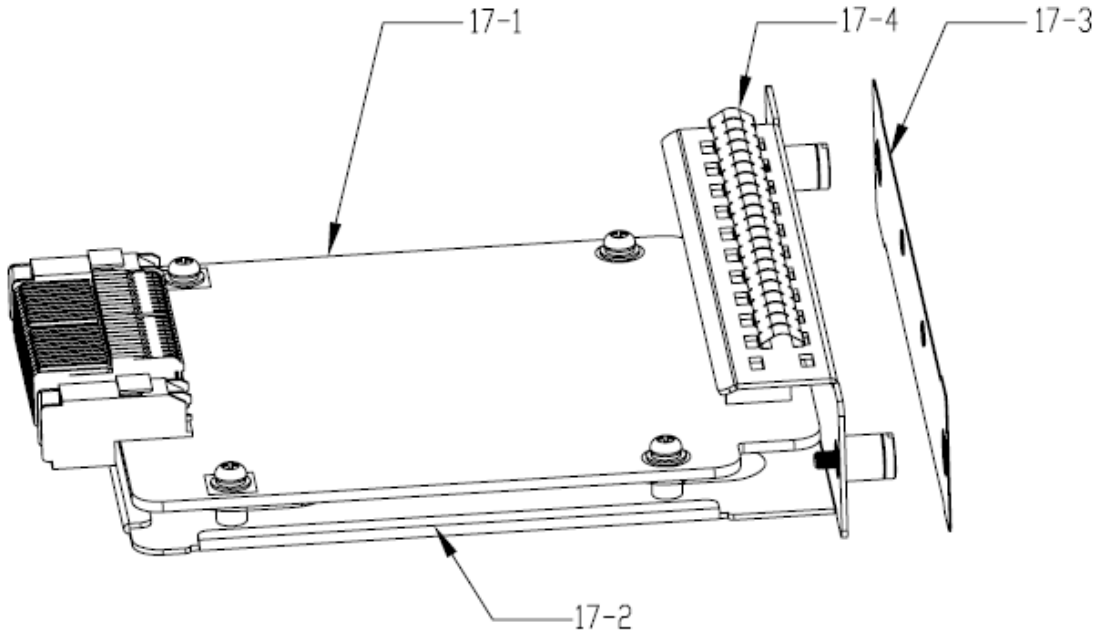

Figure 11 Treatments to front panel 17

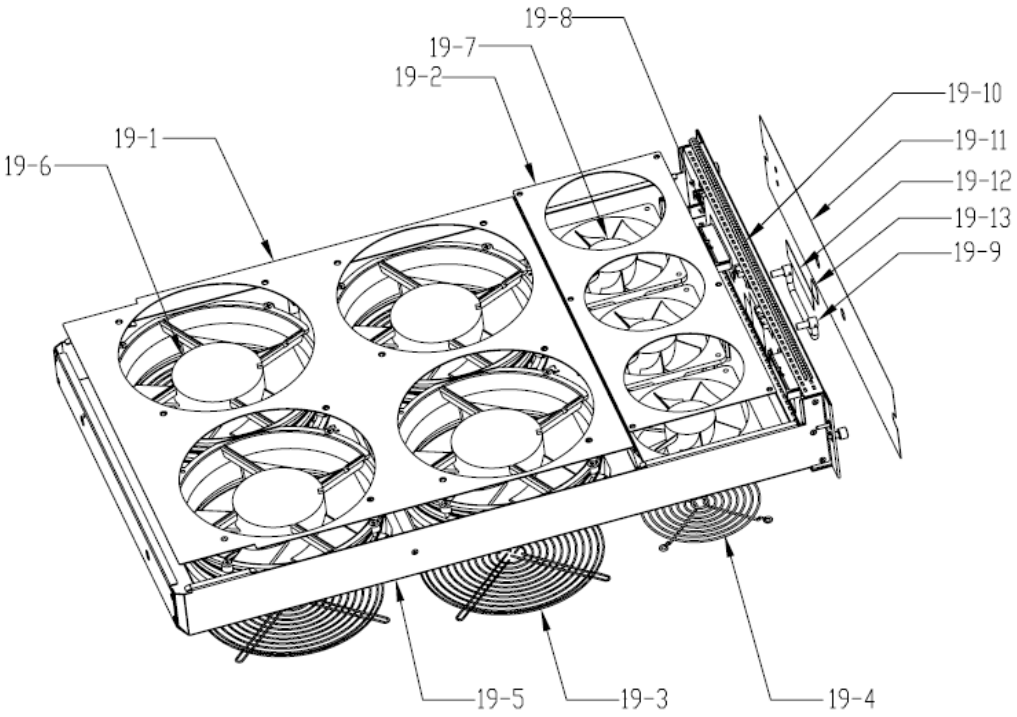

Figure 12 Treatments to Fan Tray 19

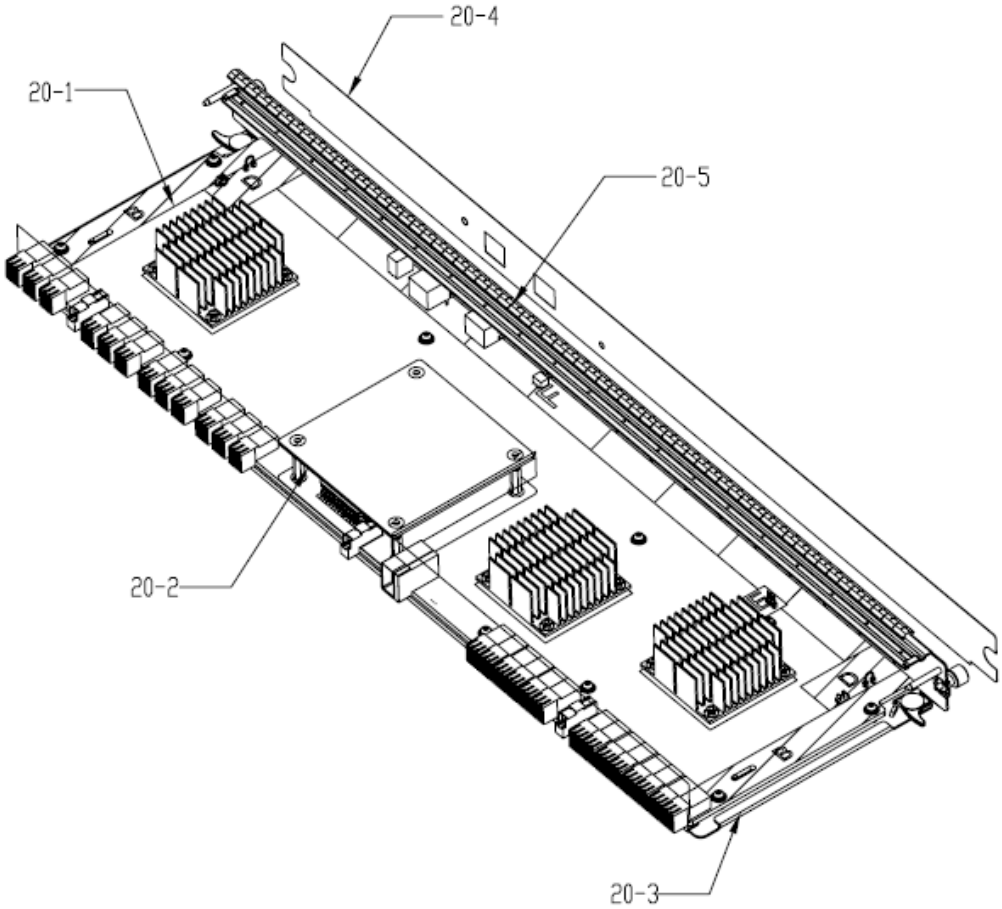

Figure 13 Treatments to panel 20

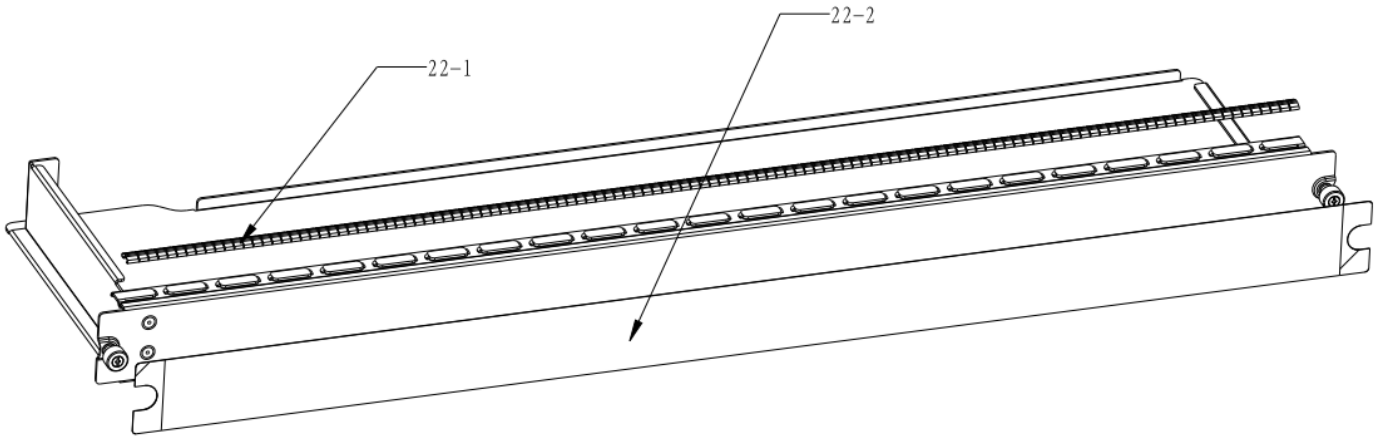

Figure 14 Treatments to panel 22

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	99377	67.83%		Fe recycling
2		Fe	4323	2.95%		Fe recycling
3						
	3-1	Complex PWB	5	0.00%	The surface of PCB is greater than 10 square centimeters;	
	3-2	Complex PWB	1733	1.18%	The surface of PCB is greater than 10 square centimeters;	
	3-3	Fe	1911	1.30%		Fe recycling
	3-6	Be-Cu	3	0.00%		Cu recycling
4						
	4-1	Complex PWB	2979	2.03%	The surface of PCB is greater than 10 square centimeters;	
	4-2	Complex PWB	5	0.00%	The surface of PCB is greater than 10 square centimeters;	
	4-3	Complex PWB	96	0.07%	The surface of PCB is greater than 10 square centimeters;	
	4-4	Al	135*5	0.46%		Al recycling
	4-5	Fe	1635	1.12%		Fe recycling
	4-6	Fe	294	0.20%		Fe recycling
	4-7	Zn	15	0.01%		Zn recycling
	4-8	Be-Cu	3	0.00%		Cu recycling

5		Fe	2021	1.38%		Fe recycling
	5-2	Be-Cu	3	0.00%		Cu recycling
7		PC	576	0.39%	Containing brominated flame retardants	
	7-1	Fe	839	0.57%		Fe recycling
	7-2	Fe	15*3	0.03%		Fe recycling
11		Fe	1212	0.83%		Fe recycling
	11-1	PC	98	0.07%	Containing brominated flame retardants	
	11-2	PC	98	0.07%	Containing brominated flame retardants	
	11-3	PC	47*9	0.29%	Containing brominated flame retardants	
16		Fe	10024	6.84%		Fe recycling
	16-3	Complex PWB	1954	1.33%	The surface of PCB is greater than 10 square centimeters;	
	16-4	Cu	22*8	0.12%		Cu recycling
	16-5	Complex PWB	1653	1.13%	The surface of PCB is greater than 10 square centimeters;	
	16-6	PC	41	0.03%	Containing brominated flame retardants	
17						
	17-1	Complex PWB	128	0.09%	The surface of PCB is greater than 10 square centimeters;	
	17-2	Fe	172	0.12%		Fe recycling
	17-3	Be-Cu	0.5	0.00%		Cu recycling
19						
	19-1	Fe	671	0.46%		Fe recycling
	19-2	Fe	198	0.14%		Fe recycling
	19-3	Fe	66*4	0.18%		Fe recycling
	19-4	Fe	40*3	0.08%		Fe recycling
	19-5	Fe	2515	1.72%		Fe recycling
	19-6	Pla,Fe	1300*4	3.55%	Containing brominated flame retardants	
	19-7	Pla,Al	200*3	0.41%	Containing brominated flame retardants	

	19-8	Complex PWB	240	0.16%	The surface of PCB is greater than 10 square centimeters;	
	19-9	Fe	40	0.03%		Fe recycling
	19-10	Be-Cu	2	0.00%		Cu recycling
20						
	20-1	Complex PWB	1338	0.91%	The surface of PCB is greater than 10 square centimeters;	
	20-2	Complex PWB	150	0.10%	The surface of PCB is greater than 10 square centimeters;	
	20-3	Fe	1355	0.92%		Fe recycling
	20-5	Be-Cu	7	0.00%		Cu recycling
22		Fe	1285	0.88%		Fe recycling
	22-1	Be-Cu	7	0.00%		Cu recycling

4. Revised record

Date	Version	Author	Modify content
2013.10.20	V0	Cai Yundi	Initial version